

DERWENT-ACC-NO: 2001-315978

DERWENT-WEEK: 200329

*Parent of mine*

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TITLE: Wiring-connecting material for use for preparing  
wiring boards comprises a polyurethane resin, a  
radical-polymerizable substance and a hardener  
that generates radicals on heating

INVENTOR: ARIFUKU, M; FUJINAWA, T ; KANAZAWA, H ; NOMURA, S ; ONO, H  
; WATANABE, I ; YUSA, M

PATENT-ASSIGNEE: HITACHI CHEM CO LTD[HITB]

PRIORITY-DATA: 2000JP-0092978 (March 28, 2000) , 1999JP-0238409 (August  
25,  
1999)

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE
PAGES MAIN-IPC		
JP 2001518652 X H05K 003/32	March 18, 2003	N/A 000
WO 200115505 A1 H05K 003/32	March 1, 2001	J 038
AU 200067314 A H05K 003/32	March 19, 2001	N/A 000
EP 1223795 A1 H05K 003/32	July 17, 2002	E 000
KR 2002034179 A C09J 009/02	May 8, 2002	N/A 000
CN 1375179 A H05K 003/32	October 16, 2002	N/A 000

DESIGNATED-STATES: AE AG AL AM AT AU AZ BA BB BG BR BY BZ CA CH CN CR  
CU CZ DE  
DK DM DZ EE ES FI GB GD GE GH GM HR HU ID IL IN IS JP KE KG KP KR KZ LC  
LK LR  
LS LT LU LV MA MD MG MK MN MW MX MZ NO NZ PL PT RO RU SD SE SG SI SK SL  
TJ TM  
TR TT TZ UA UG US UZ VN YU ZA ZW AT BE CH CY DE DK EA ES FI FR GB GH GM  
GR IE  
IT KE LS LU MC MW MZ NL OA PT SD SE SL SZ TZ UG ZW AL AT BE CH CY DE DK  
ES FI  
FR GB GR IE IT LI LT LU LV MC MK NL PT RO SE SI

APPLICATION-DATA:

PUB-NO	APPL-DESCRIPTOR	APPL-NO
APPL-DATE		
JP2001518652X	N/A	2000WO-JP05763

August 25, 2000			
JP2001518652X	N/A	2001JP-0518652	
August 25, 2000			
JP2001518652X	Based on	WO 200115505	N/A
WO 200115505A1	N/A	2000WO-JP05763	
August 25, 2000			
AU 200067314A	N/A	2000AU-0067314	
August 25, 2000			
AU 200067314A	Based on	WO 200115505	N/A
EP 1223795A1	N/A	2000EP-0955037	
August 25, 2000			
EP 1223795A1	N/A	2000WO-JP05763	
August 25, 2000			
EP 1223795A1	Based on	WO 200115505	N/A
KR2002034179A	N/A	2002KR-0702297	
February 22, 2002			
CN 1375179A	N/A	2000CN-0813017	
August 25, 2000			

INT-CL (IPC): C09J004/06, C09J009/02 , C09J175/04 , H05K003/32

ABSTRACTED-PUB-NO: WO 200115505A

BASIC-ABSTRACT:

NOVELTY - A wiring-connecting material comprises 2 - 75 parts wt. of a polyurethane resin, 30 - 60 parts wt. of a radical-polymerizable substance, and 0.1 - 30 parts wt. of a hardener that generates radicals on heating.

DETAILED DESCRIPTION - A process for preparing a wiring plate comprises connecting the connect-terminals so that they are electrically connected to each other. This process is carried out by placing the invented wiring-connecting material on a space formed between two terminals and heating with a load. The terminals are made of Au, Ag and/or Pt.

USE - The wiring-connecting material is for use for preparing wiring boards which are widely used in the electric and electronic fields.

ADVANTAGE - The wiring-connecting material has excellent hardening properties at low temperatures and excellent resistance against corrosion.

CHOSEN-DRAWING: Dwg.0/3

TITLE-TERMS: WIRE CONNECT MATERIAL PREPARATION WIRE BOARD COMPRISE POLYURETHANE

RESIN RADICAL POLYMERISE SUBSTANCE HARDEN GENERATE RADICAL HEAT

DERWENT-CLASS: A25 A85 L03 V04

CPI-CODES: A05-G01E2; A12-E07A; L03-A02E; L03-H04E;

EPI-CODES: V04-R04;

ENHANCED-POLYMER-INDEXING:

Polymer Index [1.1]

018 ; E13 E00 G1887\*R G1854 G1843 D01 D11 D10 D19 D18 D32 D50 D76  
D93 F73 ; R00895 G1592 D01 D23 D22 D31 D42 D50 D75 D84 F34 ;

H0011\*R

; P0931\*R P1592 P0839 H0260 H0011 H0044 F41 F77 D01 D63 ; P1058\*R  
P1592 P0964 H0260 F34 F77 H0044 H0011 D01 ; P1649 P1592 F77 H0011  
D01 ; P1638 P1592 F77 D01

Polymer Index [1.2]

018 ; P0986 P0964 H0293 F34 D01 D11 D10 D18 F26

Polymer Index [1.3]

018 ; ND01 ; Q9999 Q7454 Q7330 ; K9416 ; K9676\*R ; K9574 K9483

Polymer Index [2.1]

018 ; G0908 G0873 G0817 D01 D51 D54 D57 D63 D07 D78 D33 D26 D12  
D10 F90 F41 ; H0000

Polymer Index [2.2]

018 ; ND01 ; Q9999 Q7454 Q7330 ; K9416 ; K9676\*R ; K9574 K9483

Polymer Index [2.3]

018 ; R05235 D01 D11 D10 D50 D63 D94 F42 ; C999 C088\*R C000 ; C999  
C293

Polymer Index [3.1]

018 ; P0884 P1978 P0839 H0293 F41 D01 D11 D10 D19 D18 D31 D50 D63  
D90 E21 E00 ; S9999 S1285\*R

Polymer Index [3.2]

018 ; ND01 ; Q9999 Q7454 Q7330 ; K9416 ; K9676\*R ; K9574 K9483

Polymer Index [3.3]

018 ; B9999 B5447 B5414 B5403 B5276

SECONDARY-ACC-NO:

CPI Secondary Accession Numbers: C2001-097237

Non-CPI Secondary Accession Numbers: N2001-227166

DERWENT-ACC-NO: 2000-586980

DERWENT-WEEK: 200238

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TITLE: Circuit connection material for connecting  
opposing electrodes contains cationic photopolymerizable  
compound, onium salt, radical photopolymerizable compound  
having acryloyl, methacryloyl or maleimide group and  
organic peroxide

INVENTOR: FUJINAWA, T; WATANABE, I ; YANAGAWA, T ; YUSA, M

PATENT-ASSIGNEE: HITACHI CHEM CO LTD[HITB]

PRIORITY-DATA: 1999JP-0075574 (March 19, 1999) , 1999JP-0029891  
(February 8, 1999)

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE	
PAGES MAIN-IPC			
WO 200046315 A1	August 10, 2000	J	038
C09J 004/06			
JP 2000597378 X	May 28, 2002	N/A	000
C09J 004/06			
AU 200023274 A	August 25, 2000	N/A	000
C09J 004/06			
KR 2001101505 A	November 14, 2001	N/A	000
C09J 009/02			
CN 1339055 A	March 6, 2002	N/A	000
C09J 004/06			

DESIGNATED-STATES: AE AL AM AT AU AZ BA BB BG BR BY CA CH CN CR CU CZ  
DE DK DM  
EE ES FI GB GD GE GH GM HR HU ID IL IN IS JP KE KG KP KR KZ LC LK LR LS  
LT LU  
LV MA MD MG MK MN MW MX NO NZ PL PT RO RU SD SE SG SI SK SL TJ TM TR TT  
TZ UA  
UG US UZ VN YU ZA ZW AT BE CH CY DE DK EA ES FI FR GB GH GM GR IE IT KE  
LS LU  
MC MW NL OA PT SD SE SL SZ TZ UG ZW

APPLICATION-DATA:

PUB-NO	APPL-DESCRIPTOR	APPL-NO
APPL-DATE		
WO 200046315A1	N/A	2000WO-JP00666
February 8, 2000		
JP2000597378X	N/A	2000JP-0597378

DERWENT-ACC-NO: 2001-315963

DERWENT-WEEK: 200329

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TITLE: Adhesive for wiring terminal connection contains  
curing agent which generates free radicals on heating, a  
radical-polymerizable material and silicone  
particles

INVENTOR: ARIFUKU, M; FUJINAWA, T ; GOTO, Y ; KOBAYASHI, K ; MOTOMURA,  
K  
; WATANABE, I

PATENT-ASSIGNEE: HITACHI CHEM CO LTD[HITB]

PRIORITY-DATA: 1999JP-0238408 (August 25, 1999)

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE	
PAGES			
MAIN-IPC			
JP 2001518803 X	March 18, 2003	N/A	000
C09J 004/06			
WO 200114484 A1	March 1, 2001	J	036
C09J 004/06			
AU 200067317 A	March 19, 2001	N/A	000
C09J 004/06			
EP 1229095 A1	August 7, 2002	E	000
C09J 004/06			
KR 2002042649 A	June 5, 2002	N/A	000
H05K 003/34			
CN 1377393 A	October 30, 2002	N/A	000
C09J 004/06			

DESIGNATED-STATES: AE AG AL AM AT AU AZ BA BB BG BR BY BZ CA CH CN CR  
CU CZ DE  
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LK LR  
LS LT LU LV MA MD MG MK MN MW MX MZ NO NZ PL PT RO RU SD SE SG SI SK SL  
TJ TM  
TR TT TZ UA UG US UZ VN YU ZA ZW AT BE CH CY DE DK EA ES FI FR GB GH GM  
GR IE  
IT KE LS LU MC MW MZ NL OA PT SD SE SL SZ TZ UG ZW AL AT BE CH CY DE DK  
ES FI  
FR GB GR IE IT LI LT LU LV MC MK NL PT RO SE SI

APPLICATION-DATA:

PUB-NO	APPL-DESCRIPTOR	APPL-NO
APPL-DATE		
JP2001518803X	N/A	2000WO-JP05766
August 25, 2000		
JP2001518803X	N/A	2001JP-0518803

DERWENT-ACC-NO: 1998-542684

DERWENT-WEEK: 200269

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TITLE: Circuit connecting material, used in electrical  
and electronic circuits - comprises thermally free  
radical generating hardener, hydroxylated resin and  
radically polymerisable substance *This looks like Dylwand*

INVENTOR: ARIFUKU, M; FUJINAWA, T ; KANAZAWA, H ; KUWANO, A ; WATANABE, I

PATENT-ASSIGNEE: HITACHI CHEM CO LTD[HITB] , HITACHI KASEI KOGYO KK[HITB]

PRIORITY-DATA: 1997JP-0252933 (September 18, 1997) , 1997JP-0079422 (March 31, 1997) , 1997JP-0079424 (March 31, 1997)

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE
PAGES MAIN-IPC		
KR 333456 B	April 18, 2002	N/A 000
C09J 201/00		
WO 9844067 A1	October 8, 1998	J 056
C09J 201/00		
AU 9865207 A	October 22, 1998	N/A 000
C09J 201/00		
EP 979854 A1	February 16, 2000	E 000
C09J 201/00		
JP 10541457 X	September 5, 2000	N/A 000
C09J 201/00		
KR 2001005805 A	January 15, 2001	N/A 000
C09J 201/00		

DESIGNATED-STATES: AL AM AT AU AZ BA BB BG BR BY CA CH CN CU CZ DE DK  
EE ES FI  
GB GE GH GM GW HU ID IL IS JP KE KG KR KZ LC LK LR LS LT LU LV MD MG MK  
MN MW  
MX NO NZ PL PT RO RU SD SE SG SI SK SL TJ TM TR TT UA UG US UZ VN YU ZW  
AT BE  
CH DE DK EA ES FI FR GB GH GM GR IE IT KE LS LU MC MW NL OA PT SD SE SZ  
UG ZW  
DE FR GB NL

APPLICATION-DATA:

PUB-NO	APPL-DESCRIPTOR	APPL-NO
APPL-DATE		
KR 333456B	N/A	1998WO-JP01467

L Number	Hits	Search Text	DB	Time stamp
1	721	525/455.ccls.	USPAT	2003/06/27 16:56
2	310	525/455.ccls. and peroxide	USPAT	2003/06/27 16:56
3	277	(525/455.ccls. and peroxide) and (acrylate or diacrylate)	USPAT	2003/06/27 16:58